

CLAIMS:-

1. A method of forming a card embedded with at least one integrated circuit and an antenna coil, said method including the steps of (a) embedding an antenna coil onto a core sheet; (b) laminating said core sheet with at least two outer sheets to form a laminated panel; (c) forming at least a first cavity in said laminated panel to expose part of said antenna coil; (d) pulling out at least one end of said antenna coil from said core sheet; and (e) securing said integrated circuit with said antenna coil.
2. A method according to Claim 1 wherein, in said step (d), two ends of said antenna coil are pulled out from said core sheet.
3. A method according to Claim 1 or 2 wherein said antenna coil is secured with said integrated circuit by soldering or thermo compression bonding.
4. A method according to any of the preceding claims further including a step (f) of positioning a first part of said integrated circuit within said first cavity.
5. A method according to Claim 4 further including a step (g) of forming a second cavity in said laminated panel to receive a second part of said integrated circuit.
6. A method according to Claim 5 wherein said first cavity and said second cavity communicate with each other.
7. A method according to Claim 5 or 6 wherein said second cavity is narrower than said first cavity.
8. A method according to any of the preceding claims including a step (h) of applying an adhesive material on at least part of said first cavity.
9. A method according to any of the preceding claims further including a step (i) of removing an insulating coating from said end(s) of said antenna coil.
10. A card embedded with at least one integrated circuit and an antenna coil, wherein at least

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a major surface of said integrated circuit is exposed to the outside environment, wherein said antenna coil is fully embedded within said card, wherein said antenna coil is electrically connected with said integrated circuit, and wherein said antenna coil and said integrated circuit are secured with each other by soldering or thermo compression bonding.

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11. A card substantially as herein described and with reference to the accompanying drawings.

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